

SOT788-3(DD)

HVQFN28, plastic, thermally enhanced very thin quad flat, non-leaded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

17 February 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN28
Package type industry code	HVQFN28
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-01-2020
Manufacturer package code	98ASA00993D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
seated height	-	0.85	1	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	28	-	



HVQFN28, plastic, thermally enhanced very thin quad flat, non-leded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

2 Package outline

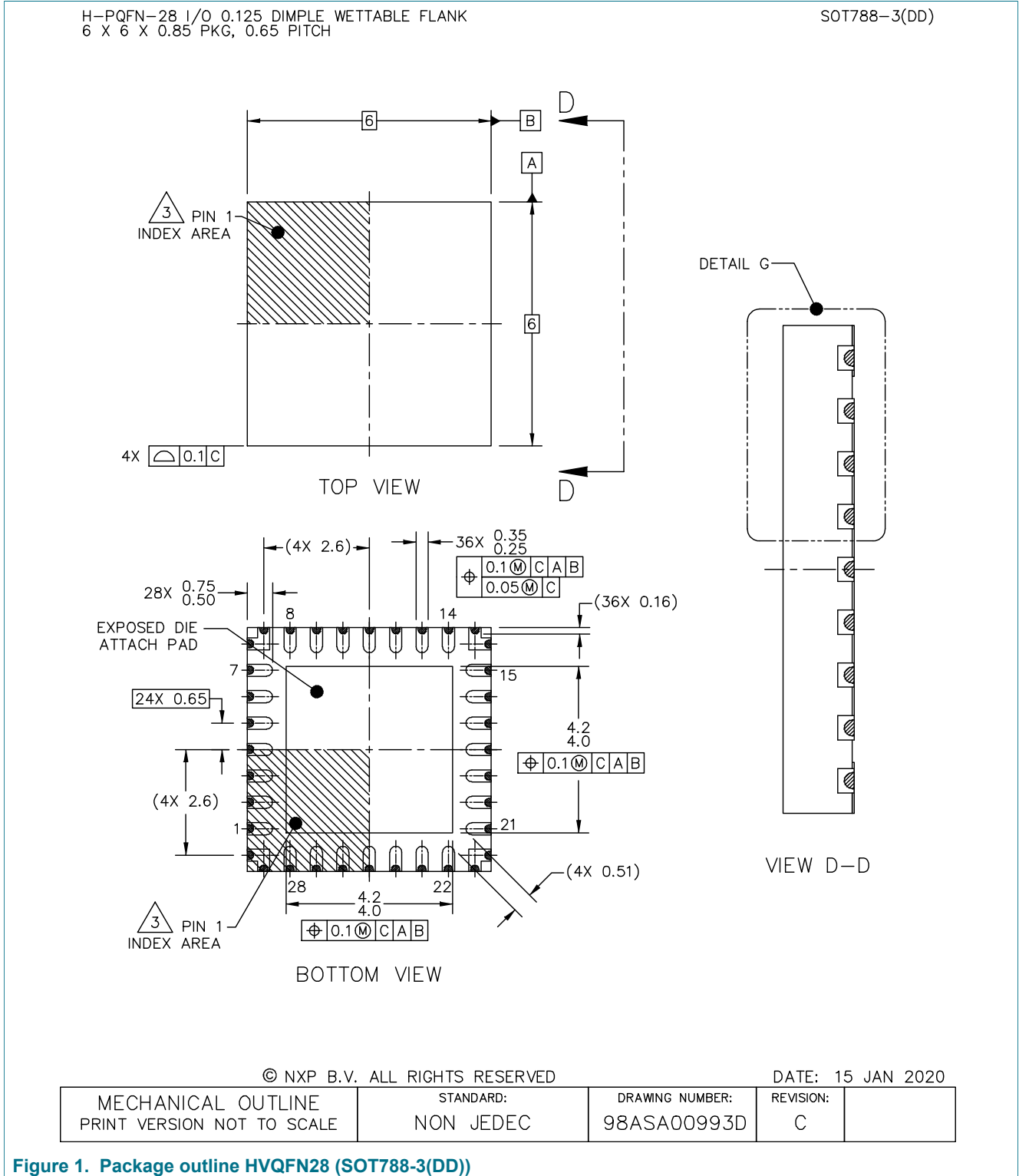
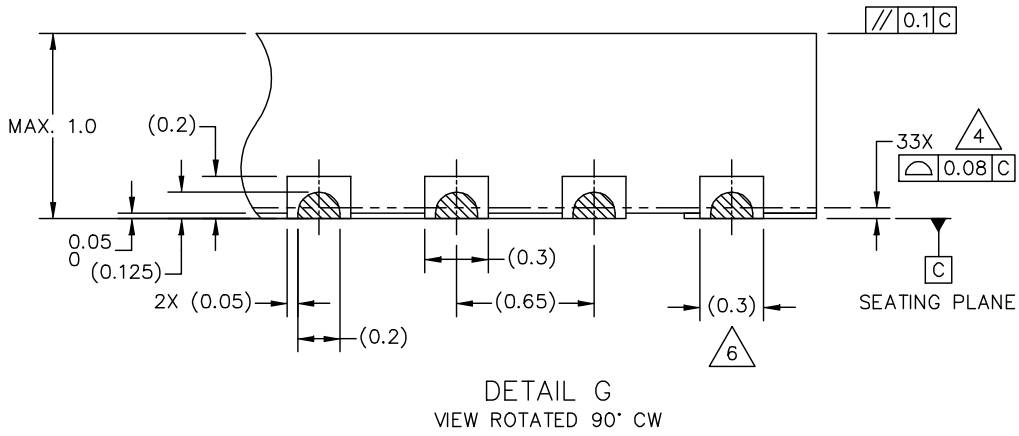


Figure 1. Package outline HVQFN28 (SOT788-3(DD))

HVQFN28, plastic, thermally enhanced very thin quad flat, non-leded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

H-PQFN-28 I/O 0.125 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.65 PITCH

SOT788-3(DD)



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Figure 2. Package outline detail HVQFN28 (SOT788-3(DD))

HVQFN28, plastic, thermally enhanced very thin quad flat, non-leaded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

3 Soldering

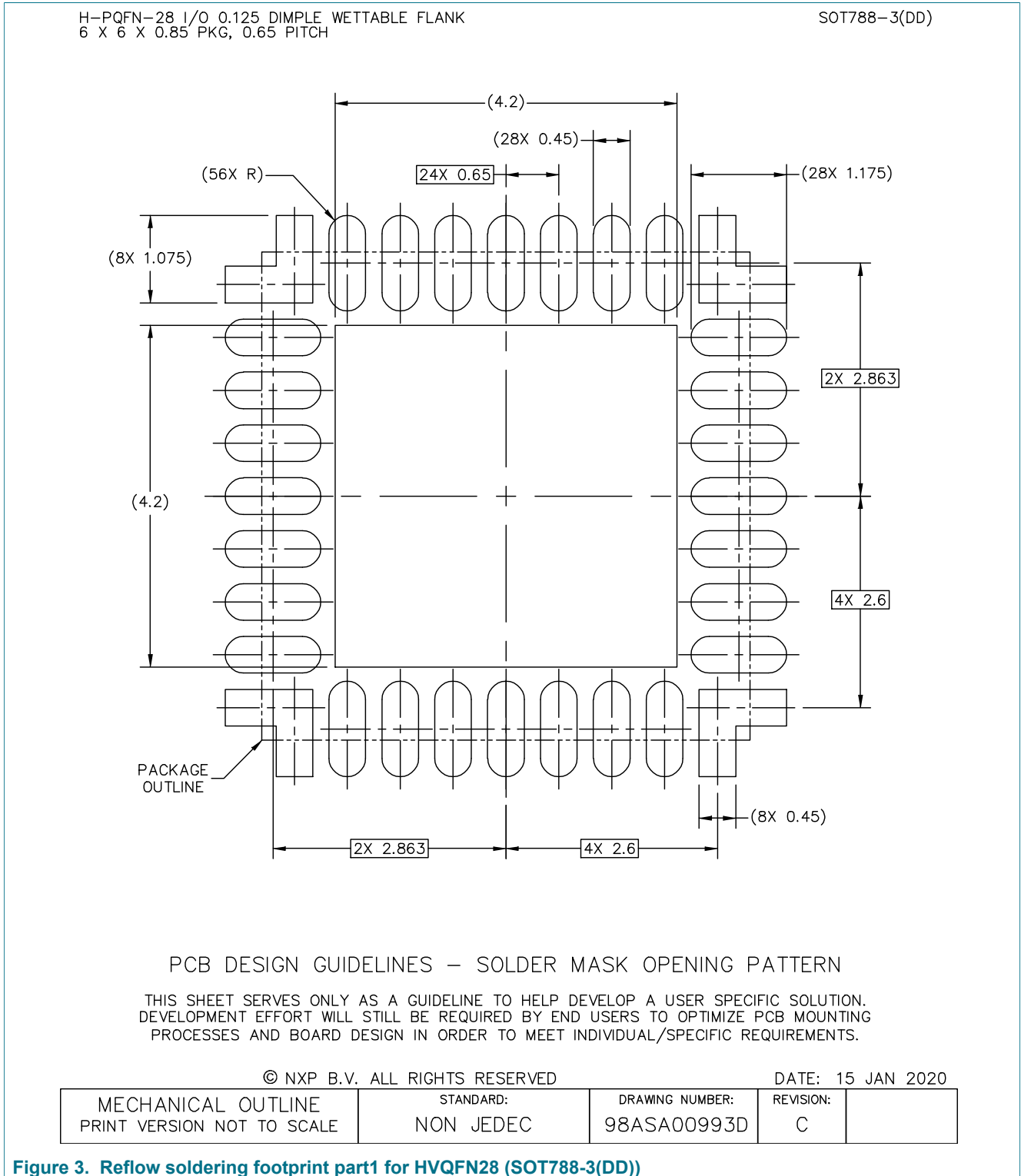


Figure 3. Reflow soldering footprint part1 for HVQFN28 (SOT788-3(DD))

HVQFN28, plastic, thermally enhanced very thin quad flat, non-leaded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

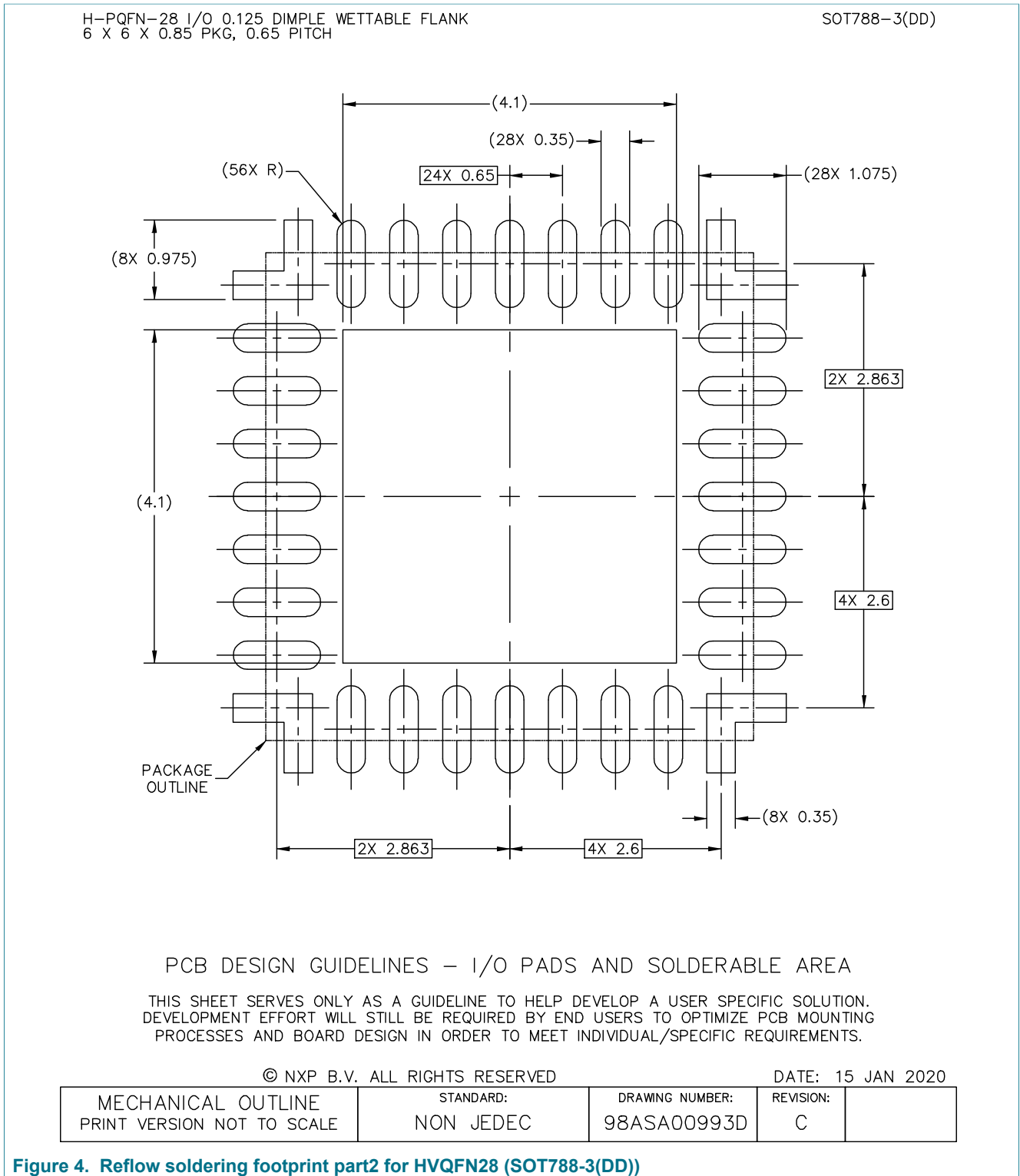


Figure 4. Reflow soldering footprint part2 for HVQFN28 (SOT788-3(DD))

HVQFN28, plastic, thermally enhanced very thin quad flat, non-leaded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

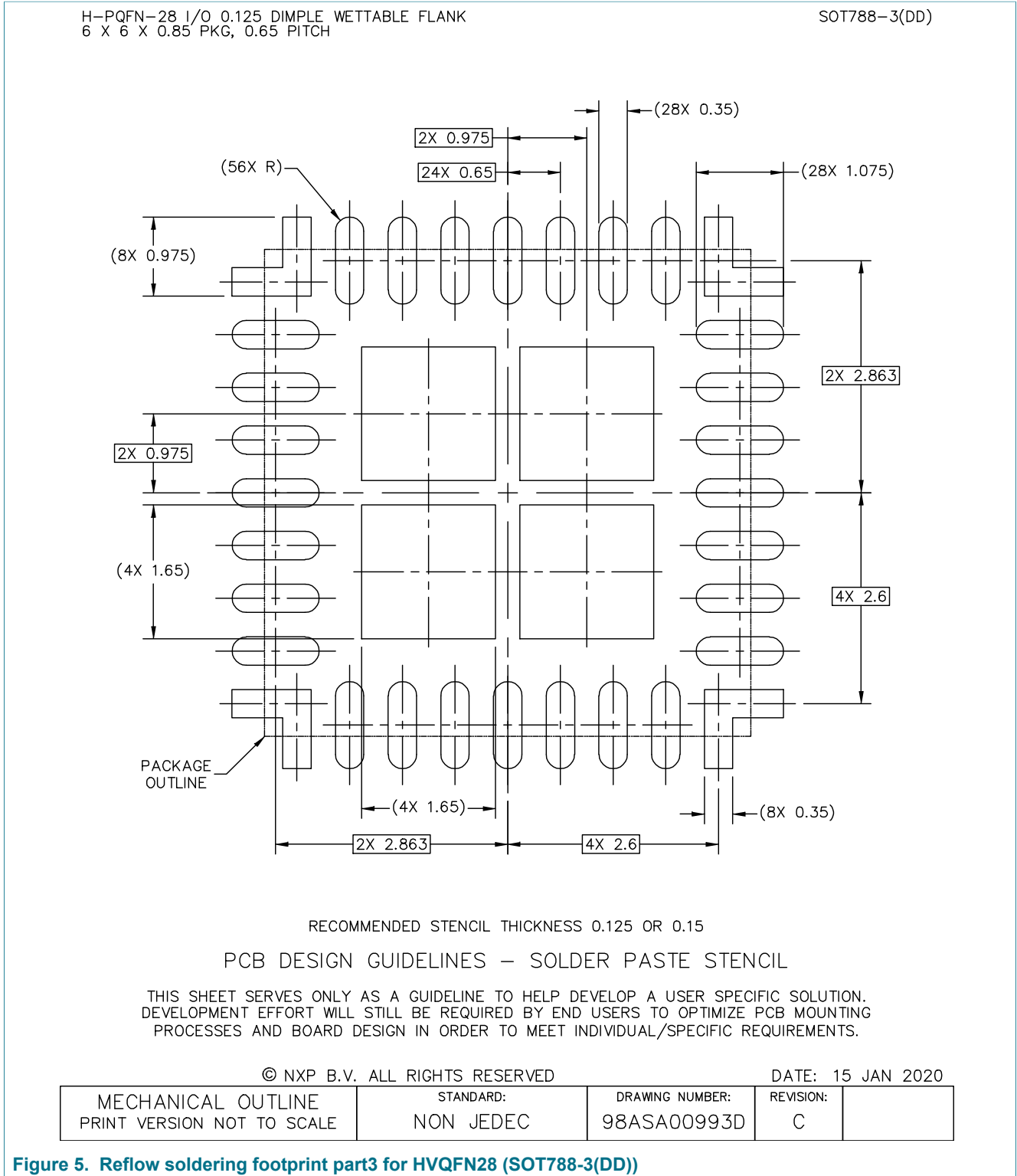


Figure 5. Reflow soldering footprint part3 for HVQFN28 (SOT788-3(DD))

HVQFN28, plastic, thermally enhanced very thin quad flat, non-leaded package, 0.125 mm dimple wettable flank; 28 terminals; 0.65 mm pitch; 6 mm x 6 mm x 0.85 mm body

H-PQFN-28 I/O 0.125 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.65 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN28 (SOT788-3(DD))

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4 Legal information

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